

IN THE SPECIFICATION:

Please amend paragraph number [0029] as follows:

[0029] Figs. 4A and 4B show two mold cavity encapsulant flow scenarios where, respectively, the lower flow front 110 and the upper flow front 108 lead the overall encapsulant flow front 106 in the cavity 44 containing the semiconductor device assembly 100. Fig. 4C depicts the advance of a flow front 106 from above, before and after ~~a die~~ a device 102 is encountered, the flow being depicted as time-separated instantaneous flow fronts 106a, 106b, 106c, 106d, 106e, and 106f. As the encapsulant flow front advances and the mold operation is completed by packing the cavities, encapsulant pressure in substantially all portions of the cavities reaches hydrostatic pressure.

Please amend paragraph number [0031] as follows:

[0031] Fig. 6 shows a bottom view of semiconductor device assembly 210. As seen in Fig. 6, dam 228 preferably extends substantially around the peripheral edges of the bottom of the heat sink ~~228~~ 216. During a transfer molding process, dam 228 serves two ~~purposes~~, purposes: (1) the dam 228 prevents damage to the mold and (2) the dam 228 prevents encapsulant molding (packaging) compound material 224 from flowing (i.e., bleeding or flashing) onto heat sink 216.